## 506212850 08/20/2020

# PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT6259593

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

#### **CONVEYING PARTY DATA**

Name	Execution Date
RENQIU WANG	02/19/2019
YI HUANG	03/25/2019
WANSHI CHEN	02/08/2019
XIAO FENG WANG	02/13/2019
PETER GAAL	02/19/2019
TAO LUO	03/11/2019
SONY AKKARAKARAN	02/07/2019

### **RECEIVING PARTY DATA**

Name:	QUALCOMM INCORPORATED	
Street Address:	eet Address: 5775 MOREHOUSE DRIVE	
City:	SAN DIEGO	
State/Country:	CALIFORNIA	
Postal Code:	92121-1714	

## **PROPERTY NUMBERS Total: 1**

Property Type	Number
Application Number:	16998115

### **CORRESPONDENCE DATA**

**Fax Number:** (303)473-2720

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

**Phone:** 303-473-2700

**Email:** dlwilliams@hollandhart.com

Correspondent Name: HOLLAND & HART LLP/QUALCOMM

Address Line 1: P.O. BOX 11583

Address Line 4: SALT LAKE CITY, UTAH 84147

ATTORNEY DOCKET NUMBER:	PN620.01.01 (93519.3006)	
NAME OF SUBMITTER:	J. SCOTT KARREN	
SIGNATURE:	/J. SCOTT KARREN/	
DATE SIGNED:	08/20/2020	

PATENT 506212850 REEL: 053550 FRAME: 0370

# **Total Attachments: 6**

source=180841 Assignment as Filed 2019-03-29.pdf\_22305487\_1#page1.tif

source=180841 Assignment as Filed 2019-03-29.pdf\_22305487\_1#page2.tif

source=180841 Assignment as Filed 2019-03-29.pdf\_22305487\_1#page3.tif

source=180841 Assignment as Filed 2019-03-29.pdf\_22305487\_1#page4.tif

source=180841 Assignment as Filed 2019-03-29.pdf\_22305487\_1#page5.tif

source=180841 Assignment as Filed 2019-03-29.pdf\_22305487\_1#page6.tif

### ASSIGNMENT

### WHEREAS, I/WE,

- 1. Renqiu WANG, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 2. Yi HUANG, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 3. Wanshi CHEN, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 4. Xiao Feng WANG, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 5. Peter GAAL, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 6. Tao LUO, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 7. Sony AKKARAKARAN, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of Poway, California.

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **UPLINK CONTROL CHANNEL RESOURCE ALLOCATION FOR NEW RADIO (NR)** (collectively the "**INVENTIONS**") for which I/WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Qualcomm Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I/WE do hereby acknowledge that I/WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not

limited to U.S. Application No. 16/188,912 filed November 13, 2018, Qualcomm Reference No. 180841, and all provisional applications relating thereto, together with U.S. Provisional Application No. 62/587,464 filed November 16, 2017, Qualcomm Reference No. 180841P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I/WE further do acknowledge and agree that I/WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I/WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I/WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I/WE may be entitled, or that I/WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I/WE HEREBY covenant and agree that I/WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I/WE HEREBY covenant that I/WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at	On LOCATION	02/19/219		and a second
racione are	LOCATION	DATE	Renqiu WANG	
Done at	LOCATION	PATE	Yi HUANG	
	Sen Dizzon.			
			Wanshi CHEN  Niao Feng WANG	
Done at	San Dily, on,	02/19/2019 DATE	Peter GAAL	
Done at	Socarron Locarron	03/11/21/2 DATT	TSO LUO	Million
Done at	SAN PIESS , on LOCATION	2/7/2019 DATE	Sony AKKARAKARAN	

#### ASSIGNMENT

### WHEREAS, I/WE,

- 1. Renqiu WANG, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 2. Yi HUANG, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 3. Wanshi CHEN, a citizen of the People's Republic of China, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 4. Xiao Feng WANG, a citizen of Canada, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 5. Peter GAAL, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 6. Tao LUO, a citizen of the United States of America, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of San Diego, California,
- 7. Sony AKKARAKARAN, a citizen of India, having a mailing address located at 5775 Morehouse Drive, San Diego, CA, 92121-1714, and a resident of Poway, California,

have conceived of one or more processes, methods, machines, articles of manufacture, designs, compositions of matter, inventions, discoveries or new or useful improvements relating to **UPLINK CONTROL CHANNEL RESOURCE ALLOCATION FOR NEW RADIO (NR)** (collectively the "**INVENTIONS**") for which I/WE have executed and/or may execute one or more patent applications therefor; and

WHEREAS, Qualcomm Incorporated (hereinafter "ASSIGNEE"), a Delaware corporation, having a place of business at 5775 Morehouse Drive, San Diego, California 92121-1714, U.S.A., desires to acquire or otherwise obtain the entire right, title, and interest in and to said INVENTIONS, including all inventions related thereto or thereof, all patent applications therefor, and all patents that have granted or may be granted hereafter thereon, including but not limited to those identified below.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I/WE do hereby acknowledge that I/WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, the entire right, title, and interest throughout the world in and to said INVENTIONS, including all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in the United States, including but not

limited to U.S. Application No. 16/188,912 filed November 13, 2018, Qualcomm Reference No. 180841, and all provisional applications relating thereto, together with U.S. Provisional Application No. 62/587,464 filed November 16, 2017, Qualcomm Reference No. 180841P1, (and do hereby authorize ASSIGNEE and its representative to hereafter add herein such application number(s) and/or filing date(s) when known), and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, and design applications thereof, and all issued patents of the United States which may have granted or may be granted hereafter thereon and all reissues, renewals, reexaminations, and extensions to any of the foregoing and all patents issuing thereon in the United States;

AND I/WE further do acknowledge and agree that I/WE have sold, assigned, conveyed, and transferred, and by these presents do hereby sell, assign, convey, and transfer, unto ASSIGNEE, its successors, its legal representatives, and its assigns, all rights of priority under International Conventions, Treaties, or Agreements, and the entire right, title, and interest throughout the world in said INVENTIONS, including all inventions related thereto or thereof, and all patent applications therefor that may have been filed or may be filed hereafter for said INVENTIONS in any foreign country, countries, or treaty/union organizations, and all divisional applications, renewal applications, continuation applications, continuation-in-part applications, patent of addition applications, confirmation applications, validation applications, utility model applications, and design applications thereof, and all issued patents which may have granted or may be granted hereafter for said INVENTIONS in any country or countries foreign to the United States, and all reissues, renewals, reexaminations, and extensions thereof;

AND I/WE DO HEREBY authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications or registrations, to issue all patents for said INVENTIONS to said ASSIGNEE, its successors, its legal representatives and its assigns, in accordance with the terms of this instrument;

AND I/WE DO HEREBY sell, assign, transfer, and convey to said ASSIGNEE, its successors, its legal representatives, and its assigns all claims for damages and all remedies arising out of or relating to any violation(s) of any of the rights assigned hereby that have or may have accrued prior to the date of assignment to said ASSIGNEE, or may accrue hereafter, including, but not limited to the right to sue for, seek, obtain, collect, recover, and retain damages and any ongoing or prospective royalties to which I/WE may be entitled, or that I/WE may collect for any infringement or from any settlement or agreement related to any of said patents before or after issuance;

AND I/WE HEREBY covenant and agree that I/WE will communicate promptly to said ASSIGNEE, its successors, its legal representatives, and its assigns, any facts known to us respecting said INVENTIONS, and will testify in any legal proceeding, sign all lawful papers, execute all applications and certificates, make all rightful declarations and/or oaths, and provide all lawful assistance to said ASSIGNEE, its successors, its legal representatives and its assigns, to obtain and enforce patent protection for said INVENTIONS in all countries;

AND I/WE HEREBY covenant that I/WE will not execute any writing or do any act whatsoever conflicting with these presents.

Done at		* 08		
	LOCATION		DATE	Rengiu WANG
Done at 🥭		, on	7/25/24/9	VIHUANG
	LOCATION		DATE	YIHUANG
Done at	~~~	, on	DATE	Wanshi CHEN
	LOCATION		DATE	Wanshi CHEN
Done at_		en	DATE	
	LOCATION		DATE	Xiao Feng WANG
Done at _	***************************************	., on	DATE	~
	LOCATION		DATE	Peter GAAL
Done at _	LOCATION	_, on _		
	LOCATION		DATE	Tao LUO
Done at _		, on	DATE:	
	LOCATION		DATE	Sony AKKARAKARAN

PATENT REEL: 053550 FRAME: 0377

**RECORDED: 08/20/2020**